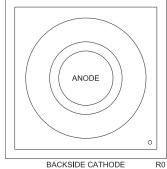


CPD66X-CMPD3003 Low Leakage Diode Die 0.2 Amp, 180 Volt

The CPD66X-CMPD3003 is a silicon 0.2 Amp, 180 Volt diode designed for low leakage applications.



٦	MECHANICAL	SPECIFICATIONS:
		01 2011 10/11101101

	Die Size	17.5 x 17.5 MILS
	Die Thickness	5.9 MILS
	Anode Bonding Pad Size	7.0 MILS DIAMETER
	Top Side Metalization	AI – 30,000Å
	Back Side Metalization	Au-As – 9,000Å
	Scribe Alley Width	2.0 MILS
	Wafer Diameter	5 INCHES
	Gross Die Per Wafer	54,848

BACKSIDE CATHODE

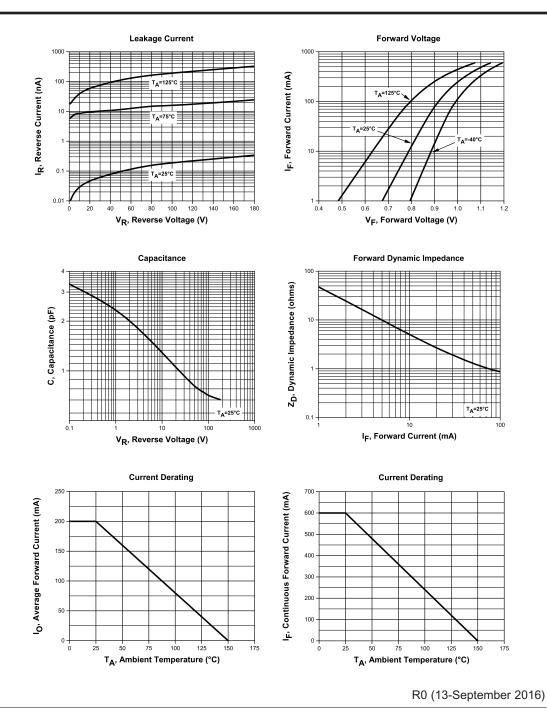
MAXIMUM R	ATINGS: (T _A =25°C)	SYMBOL		UNITS		
Continuous R	everse Voltage	VR	180	V		
Average Forv	vard Current	IO	200	mA		
Continuous Forward Current		١ _F	600	mA		
Peak Repetiti	ve Forward Current	IFRM	700	mA		
Peak Forward	d Surge Current, tp=1.0μs	^I FSM	2.0	А		
Peak Forward Surge Current, tp=1.0s		IFSM	1.0	А		
Operating and Storage Junction Temperature		T _J , T _{stg}	-65 to +150	°C		
ELECTRICAL CHARACTERISTICS: (T _A =25°C unless otherwise noted)						
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS		
I _R	V _R =125V		1.0	nA		
I _R	V _R =180V		10	nA		
ΒV _R	I _R =5.0μΑ	200		V		
VF	I _F =1.0mA	0.62	0.72	V		
VF	I _F =10mA	0.72	0.83	V		
V _F	I _F =50mA	0.80	0.89	V		
V _F	I _F =100mA	0.83	0.93	V		
VF	I _F =200mA	0.87	1.10	V		
V _F	I _F =300mA	0.90	1.15	V		
CJ	V _R =0, f=1.0MHz		4.0	pF		

R0 (13-September 2016)

CPD66X-CMPD3003 Typical Electrical Characteristics

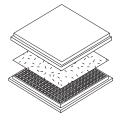


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BARE DIE PACKING OPTIONS



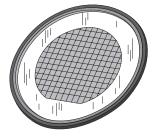


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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